Overview

HP ProBook 440 G7 Notebook PC



- 1. Internal Microphones (2)
- 2. Webcam (Optional)
- 3. Privacy Shutter (Only available with webcam)
- 4. Webcam LED
- 5. Clickpad
- 6. Hard Drive LED

- 7. SD Card Reader
- 8. Thermal Vent
- 9. USB 2.0 Port
- 10. Standard Security Lock Slot (Lock sold separately)
- 11. Power Button



Overview



Right

- 1. Power Connector
- 2. USB Type-C™ 3.1 Gen 1 Port
- 3. Ethernet Port (RJ-45)
- 4. HDMI Port (Cable not included)

- 5. USB 3.1 Gen 1 Port
- 6. USB 3.1 Gen 1 Port
- 7. Headphone/Microphone Combo Jack
- 8. HP Fingerprint Sensor (select models)



Overview

At a Glance

- Preinstall Windows 10 or FreeDOS
- Choice of 10th generation Intel® Core™ i7, i5, i3 processors
- Display include your choice of 35.56 cm (14.0") diagonal HD, Ultra Wide Viewing Angle FHD, Touch or Non-Touch screen, and Privacy Panel option
- Optional Nvidia GeForce MX250 and MX130 with 2 GB GDDR5 dedicated video memory or integrated Intel® UHD
 Graphics, Premium
- Enhanced security features including TPM 2.0, HP Sure Sense, HP Sure Start Gen5, HP BIOSphere, Hardware enforced Firmware Protection, optional Fingerprint Sensor⁴ (select models), optional IR camera, and optional Privacy Panel
- Passed 19 MIL-STD 810H testing¹
- Weight starting at 3.53 lbs (1.6 kg)³
- HP Long-Life Rechargeable battery, with HP Fast Charge Technology recharges 50% in 30 minutes²
- Supports wireless LAN and wireless WAN options for connectivity on the go
- Up to 512 GB Solid State Drives and 1 TB Hard Drive
- Up to 32 GB total system memory
- 720p HD webcam, IR camera for face authentication with Windows Hello
- Spill-resistant and optional backlit Keyboard, and Clickpad with multi-touch gestures enabled, taps enabled as
 default
- MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements
 or for military use. Test results are not a guarantee of future performance under these test conditions. Damage
 under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection
 Care Pack.
- 2. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.
- 3. Does not include power adapter.
- 4. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAME

HP ProBook 440 G7 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64¹

Windows 10 Pro 64 (National Academic only)²

Windows 10 Home 641

Windows 10 Home Single Language 641

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)1

FreeDOS

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel® Core™ i7-10510U processor with Intel® UHD Graphics, Premium (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6,7}

Intel® Core™ i5-10210U processor with Intel® UHD Graphics, Premium (1.6 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6,7}

Intel® Core™ i3-10110U processor with Intel® UHD Graphics, Premium (2.1 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores)^{3,4,5,6,7}

Processors Family

10th Generation Intel® Core™ i7 processor (i7-1050U)⁷
10th Generation Intel® Core™ i5 processor (i5-10210U)⁷
10th Generation Intel® Core™ i3 processor (i3-10110U)⁷

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
- 6. Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.
 7. In accordance with Microsoft's support policy. HP does not support the Windows 8 or Windows 7 operating system or
- 7. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



Technical Specifications

CHIPSET

Integrated with processor

GRAPHICS

Integrated

Intel® UHD Graphics, Premium8

Discrete

NVIDIA® GeForce® MX130 (2 GB DDR5 dedicated)® NVIDIA® GeForce® MX250 (2 GB DDR5 dedicated)®

Supports

Support HD decode, DX12, HDMI 1.4b up to 4K 30Hz Support CUDA, Optimus, PhysX, GPU Boost 2.0

8. HD content required to view HD images.

9. Integrated graphics depends on processor. NVIDIA® Optimus™ technology requires an Intel processor, plus an NVIDIA® GeForce® discrete graphics configuration and is available on Windows 10 Pro OS. With NVIDIA® Optimus™ technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

DISPLAYS

Non-Touch

35.56 cm (14") diagonal HD SVA eDP anti-glare slim, 220 nits, 45% NTSC two WLAN antennas (1366 x 768) $^{8.11}$

35.56 cm (14") diagonal HD SVA eDP anti-glare slim, 220 nits, 45% NTSC for HD camera and two WLAN antennas $(1366 \times 768)^{8,11}$

35.56 cm (14") diagonal HD SVA eDP anti-glare slim, 220 nits, 45% NTSC for HD+IR camera and two WLAN antennas $(1366 \times 768)^{8,11}$

35.56 cm (14") diagonal HD SVA eDP anti-glare slim, 220 nits, 45% NTSC for HD camera, WWAN and two WLAN antennas $(1366 \times 768)^{8,11}$

35.56 cm (14") diagonal FHD IPS eDP anti-glare slim, 250 nits, 45% NTSC and two WLAN antennas (1920 x 1080) 8,11

35.56 cm (14") diagonal FHD IPS eDP anti-glare slim, 250 nits, 45% NTSC for HP camera and two WLAN antennas $(1920 \times 1080)^{8,11}$

35.56 cm (14") diagonal FHD IPS eDP anti-glare slim, 250 nits, 45% NTSC for HP+IR camera and two WLAN antennas $(1920 \times 1080)^{8,11}$

35.56 cm (14") diagonal FHD IPS eDP anti-glare slim, 250 nits, 45% NTSC for HP camera, WWAN and two WLAN antennas $(1920 \times 1080)^{8,11}$

35.56 cm (14") diagonal FHD IPS eDP + PSR anti-glare flat with HP Sure View Integrated Privacy Screen, 1000 nits, 72% NTSC for HD camera and two WLAN antennas (1920 x 1080)^{8,11,12*}

35.56 cm (14") diagonal FHD IPS eDP + PSR anti-glare flat with HP Sure View Integrated Privacy Screen, 1000 nits, 72% NTSC for HD+IR camera and two WLAN antennas (1920 x 1080) 8,11,12*

Touch

35.56 cm (14") diagonal FHD IPS eDP slim touch-on-panel screen, 250 nits, 45% NTSC for HD camera and two WLAN antennas $(1920 \times 1080)^{8,10,11}$

35.56 cm (14") diagonal FHD IPS eDP slim touch-on-panel screen, 250 nits, 45% NTSC for HD camera, WWAN and two WLAN antennas (1920 x 1080) 8,10,11



Technical Specifications

HDM

Supports resolutions up to 4K 30Hz

Display Size 14" diagonal 35.56 cm (14") diagonal

8. HD content required to view HD images.

10. Sold separately or as an optional feature.

11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

12. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

*Touch-enabled display and Sure View privacy panel will lower actual brightness

Docking station model	Total number of supported displays (incl. the notebook display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock 120W G2	3	Dual 4k @60Hz	2xDP, 1xVGA, 1xTB,1xUSB-C alt-mode	Dual 4k only with one display in to DP and + TB port or USB-C alt mode + TB port
HP USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C/A Universal Dock G2	3	Dual 2.5K @ 60Hz	2xDP, 1xHDMI	
HP USB-C Dock G5	3	Dual 2.5K @ 60Hz or 4K @ 60Hz + FHD @ 60Hz	2xDP, 1xHDMI	

STORAGE AND DRIVES

Primary Storage 500 GB 7200 rpm SATA¹³ 1 TB 5400 rpm SATA¹³ 1 TB 7200 rpm SATA¹³



Technical Specifications

Primary M.2 Storage

128 GB M.2 SATA TLC Solid State Drive¹³

256 GB PCIe® NVMe™ M.2 Value Solid State Drive¹³

256 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 16 GB Intel® Optane™ memory H10^{13,14,15}

512 GB PCIe® NVMe™ M.2 TLC Solid State Drive¹³

512 GB PCIe® NVMe™ M.2 Value Solid State Drive¹³

512 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10^{13,14,15}

13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

14. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or

higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.

15. Intel® Optane™ memory H10 only for Intel® PCIe® NVMe™ QLC M.2 SSD.

MEMORY

Maximum Memory
32 GB DDR4-2666 SDRAM¹⁶

Memory

32 GB DDR4-2666 SDRAM (2 x 16 GB)¹⁶
16 GB DDR4-2666 SDRAM (1 x 16 GB)¹⁶
12 GB DDR4- 2666 SDRAM (4 GB and 8 GB (1 x 8 GB)¹⁶
8 GB DDR4-2666 SDRAM (1 x 8 GB)¹⁶
8 GB DDR4-2666 SDRAM (2 x 4 GB)¹⁶
4 GB DDR4-2666 SDRAM (1 x 4 GB)¹⁶

Memory Slots

2 SODIMM
Both slots are customer accessible / upgradeable
DDR4 PC4 SODIMMS (Comet Lake runs at 2666)
Supports Dual Channel Memory

16. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Realtek 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5 Combo¹7
Intel® Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5 Combo, non-vPro™¹7
Intel® Dual Band Wi-Fi 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro™¹7

WWAN

Intel® XMM™ 7360 LTE-Advanced (Cat9)¹⁸

Ethernet

Realtek 10/100/1000 GbE NIC¹⁹



Technical Specifications

17. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

18. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

19. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio

Integrated Microphone (Mono or Dual Array)
2 Integrated Stereo Speakers

Speaker Power

2W/4ohm Per speaker

Camera

720p HD camera⁸ 720p HD Camera+IR Camera^{8,10}

8. HD content required to view HD images. 10. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with optional backlit function

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

F1 - Display Switching

F2 - Blank or SureView On/Off

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - Numlk

F11 - Wireless

F12 - Sleep

Hidden Functions

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock



Technical Specifications

SOFTWARE AND SECURITY

BIOS

HP BIOSphere Gen5²⁰

HP Drive Lock & Automatic Drive Lock²¹

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase²²

Absolute Persistence Module²³

Pre-boot Authentication

Software

HP Connection Optimizer

HP Image Assistant

HP Hotkey Support

HP JumpStart

HP Support Assistant²⁴

HP Noise Cancellation Software

Buy Office (sold separately)

Manageability Features

HP Driver Packs²⁵

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen3²⁶

Client Security Software

HP Client Security Manager Gen5²⁷

HP Fingerprint Sensor (select models)²⁸

Windows Defender²⁹

Security Management

Pre-boot Authentication

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)

USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Click³⁰

HP Sure Start Gen531

HP Sure Sense³²



Technical Specifications

- 20. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
- 21. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives
- 22. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 23. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 24. HP Support Assistant requires Windows and Internet access.
- 25. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 26. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 27. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
- 28. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.
- 29. Windows Defender Opt in and internet connection required for updates.
- 30. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available.
- 31. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.
- 32. HP Sure Sense requires Windows 10. See product specifications for availability.

POWER

```
Power Supply
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HP Smart 65 W External AC power adapter³³
HP Smart 65 W EM External AC power adapter³³
HP Smart 65 W USB Type-C™ adapter³³
HP Smart 45 W External AC power adapter³³
HP Smart 45 W USB Type-C™ adapter³³

Primary Battery

HP Long Life 3-cell, 45 Wh Li-ion³⁴

Battery Life

Up to 14 hours and 45 minutes³⁵

Power Cord

3-wire plug - 1m³³
3-wire plug - 1.8m³³
2-wire plug - 1m³³
Duckhead power cord- 1m³³
Duckhead power cord- 1.8m³³

Battery Weight

0.49 lb

0.22 kg



Technical Specifications

- 33. Availability may vary by country.
- 34. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 35. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight

Starting at 3.53 lbs (Non-touch); Starting at 3.55 lbs (Touch)³⁶ Starting at 1.61 kg (Touch)³⁶ Does not include power adapter.

Product Dimensions (w x d x h) 12.76 x 9.36 x 0.71 in 32.42 23.77 x 1.8 cm

36. Weight will vary by configuration.

PORTS/SLOTS

1 USB 3.1 Type-C™ Gen 1 (Power delivery, DisplayPort™)
2 USB 3.1 Gen 1
1 USB 2.0 (Powered port)
1 HDMI 1.4b³7
1 RJ-45
1 AC power
1 Headphone/Microphone Combo Jack
1 Standard Security Lock

Expansion Slots
1 SD
Supports SD, SDHC, SDXC

37. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.³⁸

38. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

ENVIRONMENTAL & INDUSTRY

3.5 This product can be upgraded, po	ccibly extending it	s usoful life by s	20.0 28.7
3.5			
			20.0
2.8			
			14.2
			14.3
(LWAd, DetS)		(L	pAm, uctivets/
		Sound Pressure (L _{pAm} , decibels)	
attained for one hour.			
-			
			3 BTU/hr 1 BTU/hr
			12 BTU/hr
-	-		
			20 BTU/hr
115VAC 60Hz	2301/40	50Hz	100VAC, 50Hz
model family. HP computers mark applicable U.S. Environmental Pro computers. If a model family doe energy efficiency data listed is fo	ked with the ENER(otection Agency (E s not offer ENERGY or a typically config	iY STAR® Logo ar PA) ENERGY STAI STAR® complian pured PC featurin	e compliant with the R® specifications for t configurations, then g a hard disk drive, a high
0.37 W	0.48	W	0.37 W
0.83 W			0.81 W
3.38 W	3.44	N	3.39 W
			100VAC, 50Hz 5.81 W
The configuration used for the Energy Consumption and Declared Noise Emissions data Notebook model is based on a "Typically Configured Notebook".			ise Emissions data for the
This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: •IT ECO declaration •US ENERGY STAR® •EPEAT® 2019 Gold in U.S. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information. •TCO 8.0 •Korea Eco-label			
	may be labeled with one or more IT ECO declaration US ENERGY STAR® EPEAT® 2019 Gold in U.S. Based EPEAT®. EPEAT® status varies by TCO 8.0 Korea Eco-label The configuration used for the En Notebook model is based on a "Ty 115VAC, 60HZ 5.63 W 3.38 W 0.83 W 0.87 W Energy efficiency data listed is formodel family. HP computers mark applicable U.S. Environmental Pr computers. If a model family doe energy efficiency data listed is for efficiency power supply, and a Mi 115VAC, 60HZ 19 BTU/hr 12 BTU/hr 12 BTU/hr 13 BTU/hr Heat dissipation is calculated bas attained for one hour. Sound Power (LwAd, bels)	may be labeled with one or more of these marks: *IT ECO declaration *US ENERGY STAR* *EPEAT** 2019 Gold in U.S. Based on US EPEAT* regis EPEAT*. EPEAT* status varies by country. Visit http: *TCO 8.0 *Korea Eco-label The configuration used for the Energy Consumption Notebook model is based on a "Typically Configured 115VAC, 60Hz 230VAC, 5.63 W 3.44 W 3.44 W 3.38 W 3.44 W 3	may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® EPEAT® 2019 Gold in U.S. Based on US EPEAT® registration accordin EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.ne TCO 8.0 Korea Eco-label The configuration used for the Energy Consumption and Declared No Notebook model is based on a "Typically Configured Notebook". 115VAC, 60HZ 230VAC, 50HZ 5.63 W 3.38 W 3.44 W 0.83 W 0.79 W 0.37 W 0.48 W Energy efficiency data listed is for an ENERGY STAR® compliant prod model family. HP computers marked with the ENERGY STAR® Logo ar applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® complian energy efficiency data listed is for a typically configured PC featurin efficiency power supply, and a Microsoft Windows® operating system 115VAC, 60HZ 19 BTU/hr 12 BTU/hr 12 BTU/hr 13 BTU/hr 14 BTU/hr 15 BTU/hr 16 BTU/hr 17 BTU/hr 18 BTU/hr 18 BTU/hr 18 BTU/hr 18 BTU/hr 18 BTU/hr 19 BTU/hr 19 BTU/hr 10 BTU/hr 10 BTU/hr 10 BTU/hr 11 BTU/hr 12 BTU/hr 13 BTU/hr 14 BTU/hr 15 BTU/hr 16 BTU/hr 17 BTU/hr 18 BTU/hr



Technical Specifications

_					
	• 1 ExpressCard/54 slot				
	• 1 IEEE 1394 Port				
	• 2 SODIMM memory slots • Optional expansion base docking station				
	Optional expansion base docking station 1 multi-bay II storage port				
	• 1 multi-bay ii storage port • Interchangeable HDD				
	Spare parts are available throughout the warranty period and or for up to "5" years after the end				
	of production.				
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC				
Dutteries	This butter y(3) in this product compty with Lo Directive 2000/00/LC				
	Batteries used in the product do not contain:				
	Mercury greater the 1 ppm by weight				
	Cadmium greater than 20ppm by weight				
	Battery description: CR2032 (coin cell)				
	_	-			
	Battery type: Lithium Battery description: 6-cell high capacity Lithium-Ion battery (optional 8 cell available)				
Additional Information	_		-		
Additional information	-	ct is in compliance with the Restrictions of Hazard	ous Substances (Rons) directive -		
	2011/65/EC				
	_	oduct is designed to comply with the Waste Elec	ctrical and Electronic Equipment		
		ctive – 2002/96/EC.			
	-	ct is in compliance with California Proposition 65 (State of California; Safe Drinking		
		oxic Enforcement Act of 1986).			
	_	ict is in compliance with the IEEE 1680 (EPEAT)	standard at the Gold level, see		
	http://www.epeat.net				
	-	arts weighing over 25 grams used in the produc	t are marked per ISO11469 and		
	ISO1043. •This product contains 12.55% post-consumer recycled plastic (by wt.) according to IEEE 1680.1-2018 standard, criterion 4.2.1.1.				
	•This produ	ct is 94.3% recycle-able when properly disposed of	at end of life.		
Packaging Materials	External:	PAPER/Corrugated	0.230 g		
		Paper/Paper	0.051 g		
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	0.048 g		
		PLASTIC/Polyethylene low density	0.009 g		
Material Usage			in excess of regulatory limits		
		e HP General Specification for the Environment at			
	-	.hp.com/hpinfo/globalcitizenship/environment/po	df/gse.pdf):		
	 Asbestos 				
	Certain Azo Colorants				
	• Certain Br	ominated Flame Retardants – may not be used as fl	ame retardants in plastics		
	• Cadmium				
		ed Hydrocarbons			
	 Chlorinate 	ed Paraffins			
	• Formaldehyde				
	• Halogenat	• Halogenated Diphenyl Methanes			
	• Lead carbo	• Lead carbonates and sulfates			
	• Lead and Lead compounds				
	• Mercuric 0	Mercuric Oxide Batteries			
		nfiguration components are available in all regions/sour	_		



Technical Specifications

	Design packaging materials for ease of disassembly.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End of life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas.
- FUGSATSUTO WANDAROMONT	
End-of-life Management and Recycling	
and Recycling	To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a
	To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your
	To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information
	To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly
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Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage 19 V
Average Operating Power Win 10
Integrated graphics Yes

Discrete Graphics N17S-G2: 25 W N16S-GTR: 19 W Max Operating Power Discrete < 65 W

UMA < 45 W

Temperature

Operating 32° to 95° F (0° to 35° C) (Not writing optical)
Non-operating 41° to 95° F (5° to 35° C) (Writing optical)

Relative Humidity

Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) Maximum wet bulb temperature

Shock

Operating 40 G, 2 ms, half-sine Non-operating 200 G, 2 ms, half-sine

Random Vibration

Operating 0.75 grms
Non-operating 1.50 grms

Altitude (unpressurized)

Operating -50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating -50 to 40.000 ft (-15.24 to 12.192 m)

Planned Industry Standard

Certifications

UL Yes
CSA Yes
FCC Compliance Yes

ENERGY STAR® Selected models⁴¹

EPEAT® 2019 Gold for US, Canada, UK, Australia, New Zealand,

and India⁴²

EPEAT® 2019 Gold for other countries⁴²

ICES Yes
Australia Yes
NZ A-Tick Compliance Yes
CCC Yes
Japan VCCI Compliance Yes
KC Yes
BSMI Yes

CE Marking Compliance Yes
BNCI or BELUS Yes
CIT Yes



Technical Specifications

GOST Yes Saudi Arabian Compliance (ICCP) Yes **SABS** Yes

41. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

42. Configurations of the HP ProBook 440 G7 is ENERGY STAR® certified are identified as HP ProBook 440 G7 ENERGY STAR on HP websites and on http://www.energystar.gov.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch diagonal Outline Dimensions (W x H x D) HD (1366 x 768) Anti-Glare WLED SVA 45% NTSC 220 nits eDP 1.2 w/o PSR slim NB non-touch

316.2 x 198.04 (max.) Active Area 309.4 x 173.95 Weight <280 q max.

14.0 (inch) Diagonal Size **Thickness** 3.0 mm max Interface eDP 1.2 (1 lane) Surface Treatment **Anti-Glare**

Touch Enabled No

Contrast Ratio 300:1 (typ) Refresh Rate 60 Hz

220 nits typical (Panel Only) **Brightness**

Pixel Resolution 1366 x 768 (HD)

Format of LCD Pixel Arrangement RGB **Backlight LED**

Color Gamut Coverage 45% of NTSC Color Depth 6 bits + Hi FRC SVA 40/40/15/30 Viewing Angle

Panel LCD 14 inch diagonal Outline Dimensions ($W \times H \times D$) FHD (1920 x 1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP slim NB

316.17 x 197.98 mm (max) Active Area 309.37 x 174.02 mm (typ.)

Weight 285 q (max) Diagonal Size 14.0 inch **Thickness** 3.0 mm (max) Interface eDP 1.2 (2 lane) **Anti-Glare** Surface Treatment

Touch Enabled No

Contrast Ratio 600:1 (typ.) Refresh Rate 60 Hz



Technical Specifications

Brightness 250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 45% of NTSC

Color Depth 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 14 inch diagor FHD (1920 x 1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP slim Touch on Panel NWBZ

Panel LCD 14 inch diagonal Outline Dimensions (W x H x D) 316.112 x 197.98 mm (max)

Active Area 309.37 x 174.02 mm (typ.)

Weight 290 g (max)
Diagonal Size 14.0 inch

Thickness 3.0 mm (panel side) / 3.2 mm (PCBA Side) (max)

Interface eDP 1.2

Surface Treatment Anti-Glare On-cell

Touch Enabled Yes

Contrast Ratio 600:1 (typ.)
Refresh Rate 60 Hz
Brightness 250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 45% of NTSC

Color Depth 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72% NTSC 1000 nits eDP 1.4+PSR2 flat Privacy

Outline Dimensions (W x H x D) 315.31 x 195.498 mm (max)

Active Area 309.312 x 173.988 mm (typ.)

Weight 265 g (max)

Diagonal Size 14 inch

Thickness 3.0 mm (max)

Interface eDP 1.4 + PSR2 (4 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio 2000:1 (typ.)

Refresh Rate 60 Hz
Brightness* 1000 nits

Pixel Resolution 1920 x 1080 (FHD)



Technical Specifications

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bit

*Touch-enabled display and Sure View privacy panel will lower actual brightness

STORAGE AND DRIVES

500 GB 7200 rpm SATA Hard Drive

 Drive Weight
 0.20 lbs (92 g) ~ 0.21 lbs (95 g)

 Rotation speed
 7200 rpm

 Cache Buffer
 Up to 32 MB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate 600 MB/s

Seek Time Single Track: 2 ~ 1.5 ms;

Average: 11 ~ 13 ms; Maximum: 18 ~ 22 ms

Logical Blocks **976,773,168**

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

1 TB 5400 rpm SATA Hard

Drive

Drive Weight

Rotation speed

Cache Buffer

Height

Width

Interface

U.21 lbs (94 g)

5400 rpm

Up to 32 MB

0.28 in (7.2 mm)

2.75 in (69.85 mm)

ATA-8, SATA 3.0

Transfer Rate 600 MB/s

Seek Time Single Track2 ms

Average 12 ~ 13 ms Maximum 18 ~ 22 ms

Logical Blocks **1,953,525,168**

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

1 TB 7200 rpm SATA Hard

Drive

Drive Weight0.20 lbs (90 g)Rotation speed7200 rpmCache Buffer128 MB



Technical Specifications

 Height
 0.28 in (7.2 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate 600 MB/s

Seek Time Single Track: 1.5 ms

Average: 13 ms Maximum: 32 ms

Logical Blocks **1,953,525,168**

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

SSD 128 GB 2280 M2 SATA- Form Factor 3 TLC Capacity

Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface ATA-8, SATA 3.0
Maximum Sequential Read Up To 520 MB/s
Maximum Sequential Write Up To 450 MB/s
Logical Blocks 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3
Maximum Sequential Read Up To 1700 MB/s
Maximum Sequential Write Up To 1300 MB/s
Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

512 GB 2280 M2 PCIe NVMe Form Factor
TLC Solid State Drive Capacity

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC



Technical Specifications

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4

Maximum Sequential ReadUp To 2600 MB/sMaximum Sequential WriteUp To 1400 MB/sLogical Blocks1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

512 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 512 GB
NAND Type Value

Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm)

Weight 0.02 lb (10 g)

Interface PCIe NVMe Gen3X4

Maximum Sequential Read Up To 1500 ~ 1700 MB/s

Maximum Sequential Write Up To 860 ~ 1500MB/s

Logical Blocks **1,000,215,216**

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



Technical Specifications

NETWORKING/COMMUNICATIONS

Realtek RTL8822CE Wireless LAN Standards **IEEE 802.11a IEEE 802.11b** $802.11a/b/q/n/ac 2 \times 2$ **IEEE 802.11q** Wi-Fi® and Bluetooth® 5.0 **IEEE 802.11n IEEE 802.11ac IEEE 802.11d** IEEE 802.11e **IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v** Wi-Fi® certified Interoperability Frequency Band •802.11b/g/n 2.402 - 2.482 GHz

•802.11a/n/ac

4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode

only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationIEEE 802.11i

•WAPI

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

*Output Power*² • **802.11b: +18.5dBm minimum**

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption Transmit mode: 2.0 W



Technical Specifications

Receive mode: 1.6 W

Idle mode (PSP)180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8 g

2. Type 126: 1.3 g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF

LED OFF – Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth® Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)
Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹

BLE: 1 Mbps signaling data rate¹
1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels



Technical Specifications

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device

with a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826
Certifications Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles BT4.1-ESR 5/6/7 Compliance

Supported

LE Link Layer Ping

LE Dual Mode

LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 – Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Intel® 9560 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo¹ non-vPro Wireless LAN Standards IEEE 802.11a

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11d

IEEE 802.11e IEEE 802.11h IEEE 802.11i

IEEE 802.11k IEEE 802.11r IEEE 802.11v

Interoperability Wi-Fi® certified

Frequency Band •802.11b/g/n
2.402 - 2.482 GH

2.402 – 2.482 GHz •802.11a/n/ac

4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz

5.25 – 5.35 GHz

Not all configuration components are available in all regions/countries.

c06424517 — DA 16515 - Worldwide — Version 9 — May 26, 2020



Technical Specifications

5.47 - 5.725 GHz 5.825 - 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

> •802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

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•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

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Receive mode: 1.6 W

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Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude **Operating 0 to 10,000 ft (3,048 m)**

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber – Radio OFF

LED Off – Radio ON

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2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

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asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

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Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface USB 2.0 compliant

Bluetooth Software Micr

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826

Certifications Low Voltage Directive IEC950UL, CSA, and CE Mark

Bluetooth Profiles BT4.1-ESR 5/6/7 Compliance

Supported LE Link Layer Ping

LE Dual Mode LE Link Layer



Technical Specifications

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Intel® Wi-Fi 6 AX201 ar Bluetooth 5.0 (802.11 a/b/g/n/ac/ax (2 x 2), non-vPro, supporting gigabit file transfer speeds) non-vPro

Intel® Wi-Fi 6 AX201 and Wireless LAN Standards IEE

IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n

IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d

IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k

IEEE 802.11r IEEE 802.11v

Interoperability
Frequency Band

Wi-Fi® certified •802.11b/g/n/ax 2.402 – 2.482 GHz

•802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz

5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCSO ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode

onlv

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification



Technical Specifications

•IEEE 802.11i

•WAPI

Network Architecture

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Ad-hoc (Peer to Peer)

*Output Power*² • **802.11b:** +1**8.5dBm minimum**

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ax HT40(2.4GHz): +10dBm minimum
802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

Connected Standby 10 mW Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum
• 802.11a/g, 6Mbps: -86dBm maximum
• 802.11a/g, 54Mbps: -72dBm maximum
• 802.11n, MCS07: -67dBm maximum
• 802.11n, MCS15: -64dBm maximum
• 802.11ac, MCS0: -84dBm maximum
• 802.11ac, MCS9: -59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8 g
2. Type 126: 1.3 g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude **Operating 0 to 10,000 ft (3,048 m)**

Non-operating 0 to 50,000 ft (15,240 m)



Technical Specifications

LED Activity LED Amber – Radio OFF LED Off - Radio ON

- Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH) Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps data signaling rate up to 2.17 Mbps

BLE: 1 Mbps data signaling rate up to 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device

with a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface

USB 2.0 compliant Bluetooth Software Microsoft Windows Bluetooth Software

Supported

Link Topology

Power Management Microsoft Windows ACPI, and USB Bus Support Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

ETS 300 328. ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping **LE Dual Mode**

LE Link Layer LE Low Duty Cycle Directed Advertising **LE L2CAP Connection Oriented Channels**

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection-Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



Technical Specifications

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).

Realtek RTK8111HSH 10/100/1000 Integrated System Interface NIC

Connector **RJ-45**

PCIe + SMBus

Ethernet Features 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)

100 Mbit/s operation (100BASE-TX: IEEE 802.3u: IEEE 802.3 clauses 21-

1000 Mbit/s operation (1000BASE-T: IEEE 802.3ab: IEEE 8023 clauses

40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

Power Management ACPI compliant – multiple power modes

Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

TCP/IP/UDP Checksum Offload (configurable) Performance Features

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

Manageability Wake-on-LAN from standby and hibernation (Magic Packet and

Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB

(802.3x, clause 30)

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Management Interface Auto MDI/MDIX Crossover cable detection

Advanced CAT91

Intel® XMM™ 7360 LTE- Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300

(Band 30), 1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),



Technical Specifications

850 (Band 5), 900 (Band 8) MHz

Wireless protocol 3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to

standards 450Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

ЧHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power LTE: 1,200 mA (peak); 900 mA (average) consumption HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8 g

Dimensions **42 x 30 x 2.3 mm**

(Length x Width x Thickness)

1. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

POWER

HP 45W Smart AC adapter Dimensions ($H \times W \times D$) 3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)

Weight 0.386 lb (175 g) max

Not including power cord. Power cord varies by country.

Input 90 to 265 VAC

Input Efficiency 87.74% at 115Vac and 88.4% at 230Vac

Input frequency range 47 to 63 Hz
Input AC current 1.4 A at 90 VAC

Output Output power 45 W

DC output 19.5 V

Hold-up time 5 msec at 115 VAC input

Output current limit <8.0A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable

cords

Environmental Design Operating 32° F to 95° F (0° to 35° C)

temperature

Non-operating (storage) -4° F to 185° F (-20° to 85° C)

temperature

Altitude **0 to 16,400 ft (0 to 5,000 m)**

Humidity **20% to 95%**



Technical Specifications

Storage Humidity 10% to 95%

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC adapter Dimensions 90 x 51 x 28.5 mm

Weight 220 g +/- 10 g

Not including power cord. Power cord varies by country.

Input Input Efficiency 88% min at 115 VAC and 89% min at 230 VAC

Input frequency range 47 to 63 Hz

Input AC current 1.7 A at 90 VAC

Output Output power 65 W

DC output 19.5 V

Hold-up time 5 msec at 115 VAC input

Output current limit <11.0A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable

cords

Environmental Design Operating 32° F to 95° F (0° to 35° C)

temperature

Non-operating (storage) -4° F to 185° F (-20° to 85° C)

temperature

Altitude **0 to 16,400 ft (0 to 5000m)**

Humidity 20% to 95% Storage Humidity 10% to 95%

EMI and Safety Certifications Eg:*CE Mark - full compliance with LVD and EMC directives* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B,

approvals - C-UL-US, NUKDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.* MTBF - over 200,000 hours at 25°C

ambient condition.

HP 65W EM Smart AC adapter

Dimensions

102 x 55 x 30 mm

Weight 270 g +/- 10 g

Not including power cord. Power cord varies by country.

Input Input Efficiency 87% min at 115V/230V

Input frequency range 47 to 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

DC output 65 W(19.5V/3.33A)
Hold-up time 5 msec at 115 VAC input

Output current limit <11A, Over voltage protection- 29V max

automatic shutdown



Technical Specifications

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable

cords

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 5,000 m

Humidity 0% to 95%

Storage Humidity 0% to 95%

EMI and Safety Certifications CE Mark - EMC directives; Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; Reliability - failure rate of less than 0.1% annually within the first three years of operation. * MTBF - over 200,000 hours

at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions
USB type C

Dimensions 74 x 74 x 28.5 mm

Weight 245 g +/- 10 g

Not including power cord. Power cord varies by country.

Input Input Efficiency

81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 to 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output power 65 W

DC output 5V/9V/10V/12V/15V/20V
Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector Type C

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000 m)

Humidity 5% to 95% Storage Humidity 5% to 95%

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.



Technical Specifications

AC Adapter 45 Watt nPFC Dimensions

62.0 x 62.0 x 28.5 mm

USB type C

Weight 220 q +/- 10 q

Not including power cord. Power cord varies by country.

Input Input Efficiency Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:5V: 81.5%9V: 86.7%10V: 87.5%12V:

87.8%15V: 87.8%20V: 87.8%

Input frequency range 47 to 63 Hz

Input AC current Max. 1.4 A at 90 Vac

5V/15W Output power

9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W

5V/9V/10V/12V/15V/20V DC output Hold-up time 5ms at 115 Vac input

<5.0A Output current limit

Connector Type C

Environmental Design **Operating** 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% Storage Humidity 10% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200.000 hours at 25°C ambient condition.

3 Cell WHr 45 Long Life -Polymer HP Fast Charge Technology¹

Dimensions 3.900 Ah Weight 45 Wh Connector Type C

Energy 32° to 113° F (0° to 45° C) Voltage 14° to 122° F (-10° to 60° C)

Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.



Technical Specifications

FINGERPRINT READER

Model Synaptics Validity VFS7604 touch sensor

Mobile Voltage Operation 3.0V to 3.6V
Operating Temperature 0~60°C
Current Consumption Image 100mA Max

Low Latency Wait For Finger 260 uA

ESD Resistance IEC 61000-4-2 4B (+/-15KV)

Detection Matrix 363 dpi / 7.4 x 6 mm sensor area

FRR (False Reject Rate) / FAR FRR <1% @ 1:50K FAR

(False Acceptance Rate)



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Essential Messenger Case (up to 17.3")	H1D25AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Dock G4 (Mockingjay 3.0)	3FF69AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Dock G5	5TW10AA
	HP E223d Docking Monitor	5VT82A8
		5VT82AA
	HP E243d Docking Monitor	1TJ76AA
	HP E273d Docking Monitor	5WN63A8 5WN63AA
	HP EliteDisplay E244d Monitor	6PA50A8
	THE Efficients play E2440 Profittor	6PA50AA
	HP EliteDisplay E274d Monitor	6PA56A8
		6PA56AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C Travel Hub	Z9G82AA
Memory	4G B 2666MHz DDR4	4VN05AA
Memory	8 GB 2666MHz DDR4	4VN06AA
	16 GB 2666MHz DDR4	4VN07AA
	וט פט בטטטויוווב ששת-	4VNU/AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	45W Smart Power Adapter 2 prong -4.5mm (Japan only)	L6F60AA
	65W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y89AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Slim Power Adapter	3PN48AA



Options and Accessories (sold separately and availability may vary by country)

	HP 65W USB-C Power Adapter	1HE08AA
	HP 45W USB-C Power Adapter	1HEO7AA
	HP Power Bank	N9F71AA
	HP USB-C Power Bank	2NA10AA
Storage	HP External USB Optical Drive	F2B56AA
	HP 128 GB M.2 SATA-3	2JB95AA
	1TB 7200rpm 9.5mm SATA HDD	L3M56AA
	HP 500 GB 7200rpm HDD	F3B97AA
	HP 256 GB TLC PCI-e 3x4 NVMe SSD (2280)	1FU87AA
	HP 512 GB TLC PCI-e 3x4 NVMe SSD (2280)	1FU88AA
Security	HP Combination Lock	TOY15AA
	HP Essential Keyed Cable lock 12.3mm	TOY14AA
	HP Keyed Cable Lock 10mm	T1A62AA
UCC	HP Conferencing Keyboard	K8P74AA
	HP UC Speaker Phone	4VW02AA
	HP Wired Headset	K7V17AA



Summary of Changes

Date of change:	Version History:		Description of change:
October 30, 2019	V1 to V2	Added	Environmental Section and updated Battery Life
November 4, 2019	V2 to V3	Updated	UHD Graphics
February 12, 2020	V3 to V4	Added	HP Sure Sense
February 27, 2020	V4 to V5	Updated	Copyright and footnote for fingerprint sensor.
March 2, 2020	V5 to V6	Updated	Call out numbers, Webcam and Privacy Shutter
April 14, 2020	V6 to V7	Updated	EPEAT
April 22, 2020	V7 to V8	Updated	Networking / Communications section
May 26, 2020	V8 to V9	Updated	Military Standards Information /Ethernet network

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